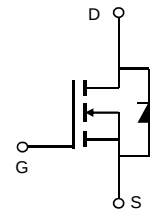
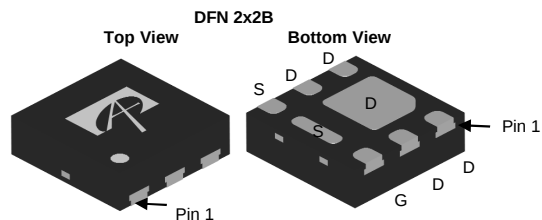


General Description

The AON2408 combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

Product Summary

V_{DS}	20V
I_D (at $V_{GS}=4.5V$)	8A
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	< 14.5m Ω
$R_{DS(ON)}$ (at $V_{GS}=2.5V$)	< 19m Ω



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^G	I_D	8	A
$T_A=25^\circ\text{C}$			
$T_A=100^\circ\text{C}$		6	
Pulsed Drain Current ^C	I_{DM}	32	
Power Dissipation ^A	P_D	2.8	W
$T_A=25^\circ\text{C}$			
$T_A=70^\circ\text{C}$		1.8	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	37	45	$^\circ\text{C/W}$
$t \leq 10s$				
Maximum Junction-to-Ambient ^{A D}		66	80	$^\circ\text{C/W}$
Steady-State				

Electrical Characteristics (T_j=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V T _j =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±12V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.5	0.83	1.2	V
I _{D(ON)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	32			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =8A T _j =125°C		11.6 16.3	14.5 20.5	mΩ
		V _{GS} =2.5V, I _D =4A		15	19	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =8A		50		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.65	1	V
I _S	Maximum Body-Diode Continuous Current				3.5	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, f=1MHz		782		pF
C _{oss}	Output Capacitance			158		pF
C _{rss}	Reverse Transfer Capacitance			98		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		2.4		Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =10V, I _D =8A		7		nC
Q _{gs}	Gate Source Charge			1		nC
Q _{gd}	Gate Drain Charge			2.4		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =4.5V, V _{DS} =10V, R _L =1.25Ω, R _{GEN} =3Ω		3		ns
t _r	Turn-On Rise Time			4.5		ns
t _{D(off)}	Turn-Off DelayTime			28		ns
t _f	Turn-Off Fall Time			6		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =8A, dI/dt=100A/μs		11		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =8A, dI/dt=100A/μs		2.7		nC

- A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The Power dissipation P_{DSM} is based on R_{θJA} t ≤ 10s value and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design.
- B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C. Ratings are based on low frequency and duty cycles to keep initial T_j=25° C.
- D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.
- E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.
- F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.
- G. The maximum current rating is package limited.
- H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

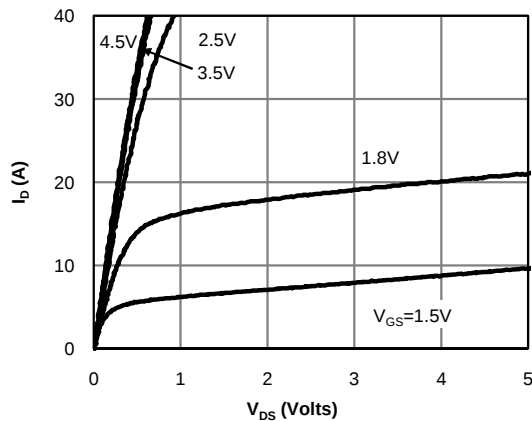


Fig 1: On-Region Characteristics (Note E)

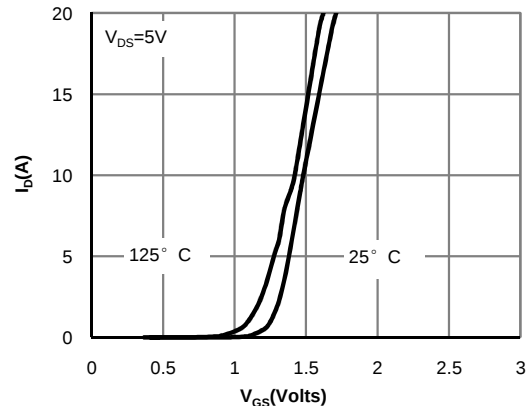


Figure 2: Transfer Characteristics (Note E)

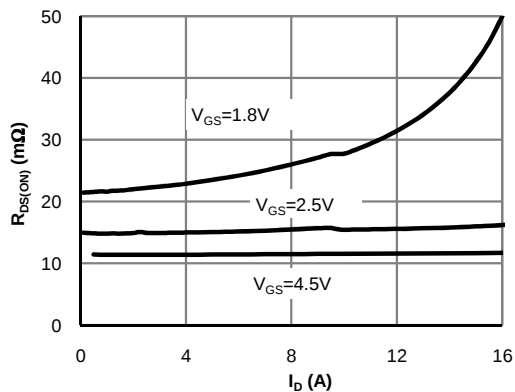


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

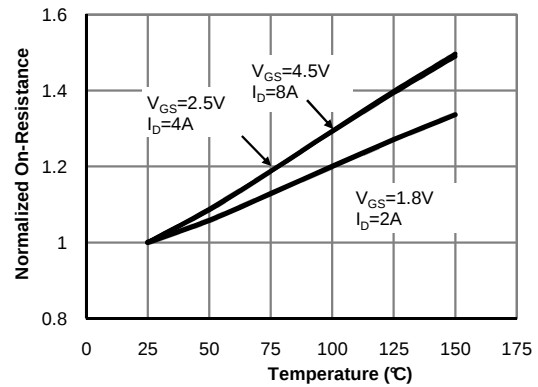


Figure 4: On-Resistance vs. Junction Temperature (Note E)

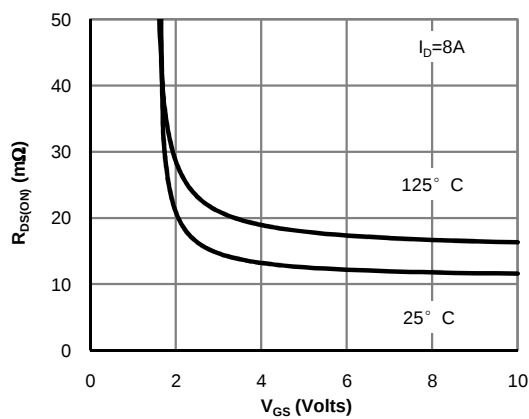


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

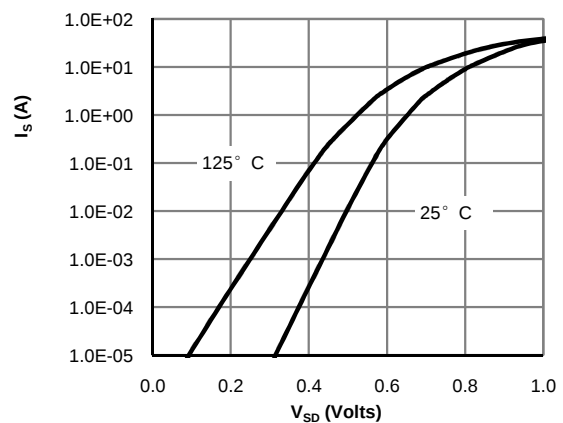


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

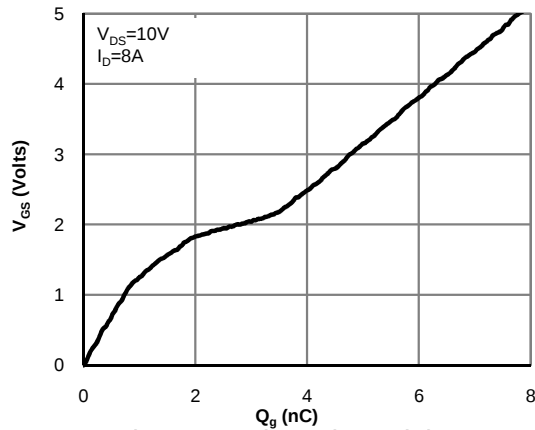


Figure 7: Gate-Charge Characteristics

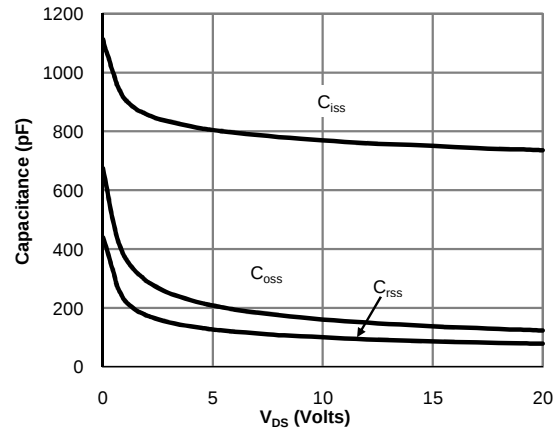


Figure 8: Capacitance Characteristics

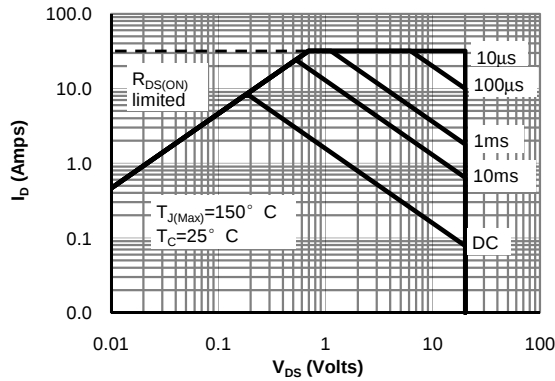


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

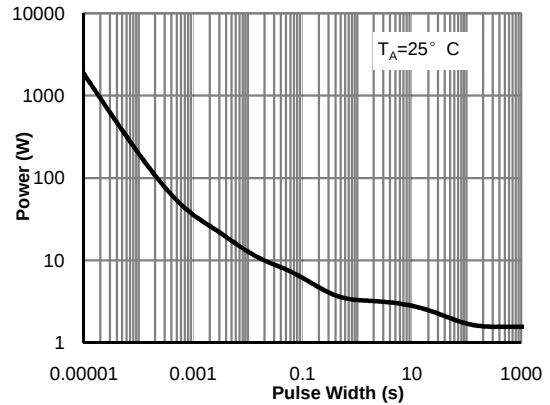


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note H)

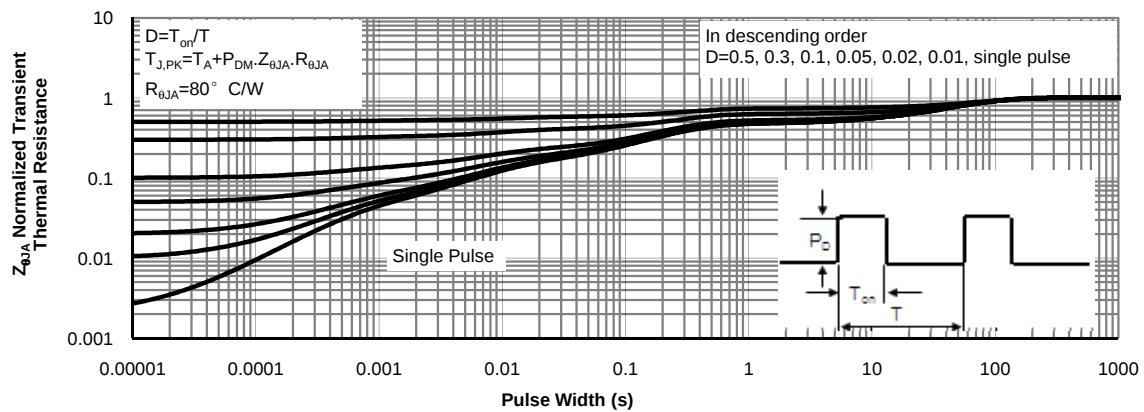
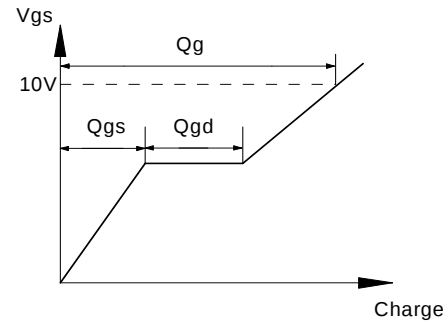
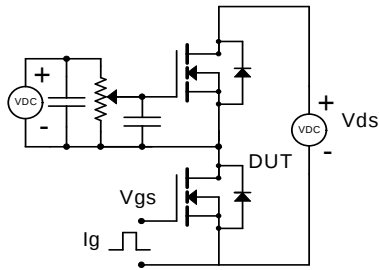
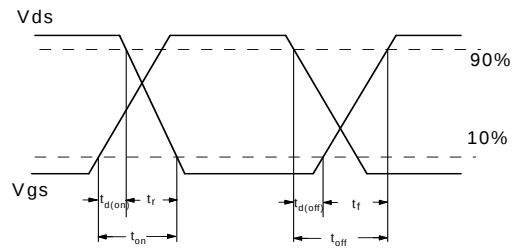
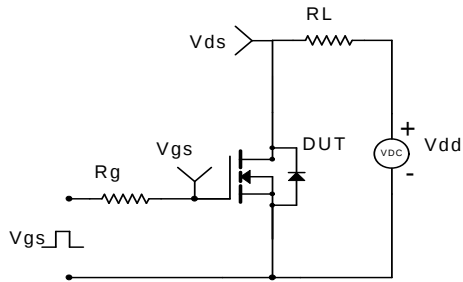


Figure 12: Normalized Maximum Transient Thermal Impedance (Note H)

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

